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Understanding [Embedded - FPGAs \(Field Programmable Gate Array\)](#)

Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details

| | |
|--------------------------------|---|
| Product Status | Obsolete |
| Number of LABs/CLBs | - |
| Number of Logic Elements/Cells | 1568 |
| Total RAM Bits | 25600 |
| Number of I/O | 171 |
| Number of Gates | 48000 |
| Voltage - Supply | 3V ~ 3.6V |
| Mounting Type | Surface Mount |
| Operating Temperature | -40°C ~ 85°C (TA) |
| Package / Case | 208-BFQFP |
| Supplier Device Package | 208-PQFP (28x28) |
| Purchase URL | https://www.e-xfl.com/product-detail/lattice-semiconductor/or3t306s208i-db |

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SELECT DEVICES
DISCONTINUED

System-Level Features

System-level features reduce glue logic requirements and make a system on a chip possible. These features in the *ORCA* Series 3 include:

- Full PCI local bus compliance.
- Dual-use microprocessor interface (MPI) can be used for configuration, readback, device control, and device status, as well as for a general-purpose interface to the FPGA. Glueless interface to *i960** and *PowerPC*† processors with user-configurable address space provided.
- Parallel readback of configuration data capability with the built-in microprocessor interface.
- Programmable clock manager (PCM) adjusts clock

phase and duty cycle for input clock rates from 5 MHz to 120 MHz. The PCM may be combined with FPGA logic to create complex functions, such as digital phase-locked loops (DPLL), frequency counters, and frequency synthesizers or clock doublers. Two PCMs are provided per device.

- True, internal, 3-state, bidirectional buses with simple control provided by the SLIC.
- 32 x 4 RAM per PFU, configurable as single- or dual-port at >176 MHz. Create large, fast RAM/ROM blocks (128 x 8 in only eight PFUs) using the SLIC decoders as bank drivers.

* *i960* is a registered trademark of Intel Corporation.

† *PowerPC* is a registered trademark of International Business Machines Corporation.

Table 2. *ORCA* Series 3 System Performance

| Parameter | # PFUs | Speed | | | | Unit |
|---|--------|-------|-------|------|------|------|
| | | -4 | -5 | -6 | -7 | |
| 16-bit Loadable Up/Down Counter | 2 | 78 | 102 | 131 | 168 | MHz |
| 16-bit Accumulator | 2 | 78 | 102 | 131 | 168 | MHz |
| 8 x 8 Parallel Multiplier: | | | | | | |
| Multiplier Mode, Unpipelined ¹ | 11.5 | 19 | 25 | 30 | 38 | MHz |
| ROM Mode, Unpipelined ² | 8 | 51 | 66 | 80 | 102 | MHz |
| Multiplier Mode, Pipelined ³ | 15 | 76 | 104 | 127 | 166 | MHz |
| 32 x 16 RAM (synchronous): | | | | | | |
| Single-port, 3-state Bus ⁴ | 4 | 97 | 127 | 151 | 192 | MHz |
| Dual-port ⁵ | 4 | 127 | 166 | 203 | 253 | MHz |
| 128 x 8 RAM (synchronous): | | | | | | |
| Single-port, 3-state Bus ⁴ | 8 | 88 | 116 | 139 | 176 | MHz |
| Dual-port ⁵ | 8 | 88 | 116 | 139 | 176 | MHz |
| 8-bit Address Decode (internal): | | | | | | |
| Using Softwired LUTs | 0.25 | 4.87 | 3.66 | 2.58 | 2.03 | ns |
| Using SLICs ⁶ | 0 | 2.35 | 1.82 | 1.23 | 0.99 | ns |
| 32-bit Address Decode (internal): | | | | | | |
| Using Softwired LUTs | 2 | 16.06 | 12.07 | 9.01 | 7.03 | ns |
| Using SLICs ⁷ | 0 | 6.91 | 5.41 | 4.21 | 3.37 | ns |
| 36-bit Parity Check (internal) | 2 | 16.06 | 12.07 | 9.01 | 7.03 | ns |

1. Implemented using 8 x 1 multiplier mode (unpipelined), register-to-register, two 8-bit inputs, one 16-bit output.

2. Implemented using two 32 x 12 ROMs and one 12-bit adder, one 8-bit input, one fixed operand, one 16-bit output.

3. Implemented using 8 x 1 multiplier mode (fully pipelined), two 8-bit inputs, one 16-bit output (7 of 15 PFUs contain only pipelining registers).

4. Implemented using 32 x 4 RAM mode with read data on 3-state buffer to bidirectional read/write bus.

5. Implemented using 32 x 4 dual-port RAM mode.

6. Implemented in one partially occupied SLIC with decoded output set up to CE in same PLC.

7. Implemented in five partially occupied SLICs.

Programmable Logic Cells (continued)

In the third submode, **multiplier submode**, a single PFU can affect an 8 x 1 bit (4 x 1 for half-ripple mode) multiply and sum with a partial product (see Figure 8). The multiplier bit is input at ASWE, and the multiplicand bits are input at Kz[1], where K7[1] is the most significant bit (MSB). Kz[0] contains the partial product (or other input to be summed) from a previous stage. If ASWE is logical 1, the multiplicand is added to the partial product. If ASWE is logical 0, 0 is added to the partial product, which is the same as passing the partial product. CIN/FCIN can bring the carry-in from the less significant PFUs if the multiplicand is wider than 8 bits, and COUT/FCOUT holds any carry-out from the multiplication, which may then be used as part of the product or routed to another PFU in multiplier mode for multiplicand width expansion.

Ripple mode's fourth submode features **equality comparators**. The functions that are explicitly available are $A > B$, $A \neq B$, and $A < B$, where the value for A is input on Kz[0], and the value for B is input on Kz[1]. A value of 1 on the carry-out signals valid argument. For example, a carry-out equal to 1 in AB submode indicates that the value on Kz[0] is greater than or equal to the value on Kz[1]. Conversely, the functions $A < B$, $A + B$, and $A > B$ are available using the same functions but with a 0 output expected. For example, $A > B$ with a 0 output indicates $A < B$. Table 5 shows each function and the output expected.

If larger than 8 bits, the carry-out signal can be cascaded using fast-carry logic to the carry-in of any adjacent PFU. The use of this submode could be shown using Figure 6, except that the CIN/FCIN input for the least significant PFU is controlled via configuration.

Table 5. Ripple Mode Equality Comparator Functions and Outputs

| Equality Function | ispLEVER Submode | True, if Carry-Out Is: |
|-------------------|------------------|------------------------|
| $A > B$ | $A > B$ | 1 |
| $A < B$ | $A < B$ | 1 |
| $A \neq B$ | $A \neq B$ | 1 |
| $A < B$ | $A > B$ | 0 |
| $A > B$ | $A < B$ | 0 |
| $A = B$ | $A \neq B$ | 0 |

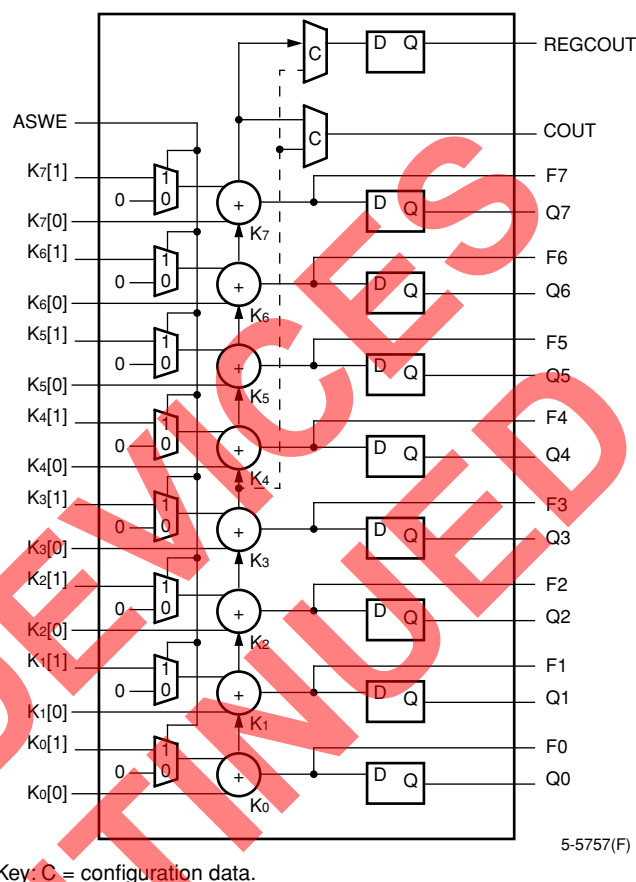


Figure 8. Multiplier Submode

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Figure 13. Buffer-Buffer-Decoder Mode

Figure 14. Buffer-Decoder-Buffer Mode

Programmable Logic Cells (continued)

PLC Routing Resources

Generally, the ispLEVER Development System is used to automatically route interconnections. Interactive routing with the ispLEVER design editor (EPIC) is also available for design optimization. To use EPIC for interactive layout, an understanding of the routing resources is needed and is provided in this section.

The routing resources consist of switching circuitry and metal interconnect segments. Generally, the metal lines which carry the signals are designated as routing segments. The switching circuitry connects the routing segments, providing one or more of three basic functions: signal switching, amplification, and isolation. A net running from a PFU or PIC output (source) to a PLC or PIC input (destination) consists of one or more routing segments, connected by switching circuitry called configurable interconnect points (CIPs).

The following sections discuss PLC, PIC, and interquad routing resources. This section discusses the PLC switching circuitry, intra-PLC routing, inter-PLC routing, and clock distribution.

Configurable Interconnect Points

The process of connecting routing segments uses three basic types of switching circuits: two types of configurable interconnect points (CIPs) and bidirectional buffers (BIDs). The basic element in CIPs is one or more pass transistors, each controlled by a configuration RAM bit. The two types of CIPs are the mutually exclusive (or multiplexed) CIP and the independent CIP.

A mutually exclusive set of CIPs contains two or more CIPs, only one of which can be on at a time. An independent CIP has no such restrictions and can be on independent of the state of other CIPs. Figure 18 shows an example of both types of CIPs.

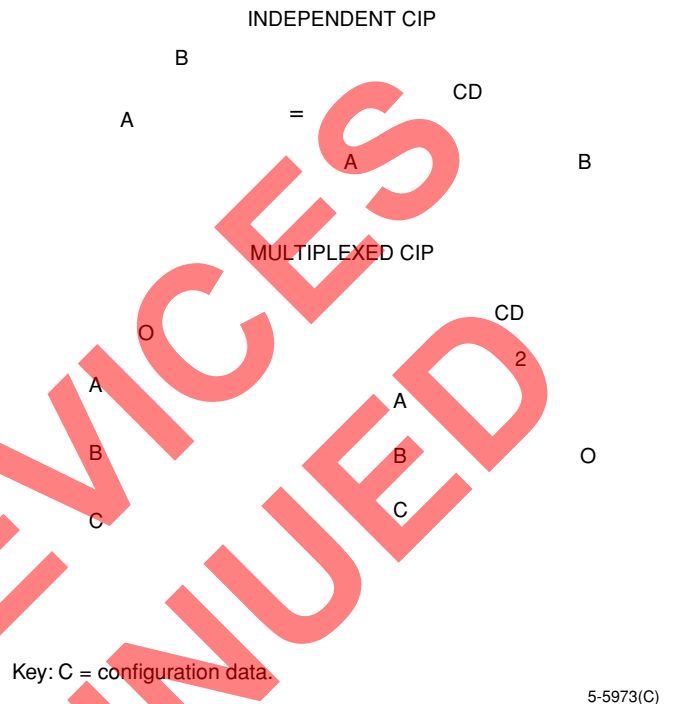


Figure 18. Configurable Interconnect Point

3-State Bidirectional Buffers

Bidirectional buffers, previously described in the SLIC section of the programmable logic cell discussion, provide isolation as well as amplification for signals routed a long distance. Bidirectional buffers are also used to route signals diagonally in the PLC (described later in the subsection entitled Intra-PLC Routing), and BIDs can be used to indirectly route signals through the switching routing (xSW) segments. Any number from zero to ten BIDs can be used in a given PLC.

Special Function Blocks (continued)

Start-Up Logic

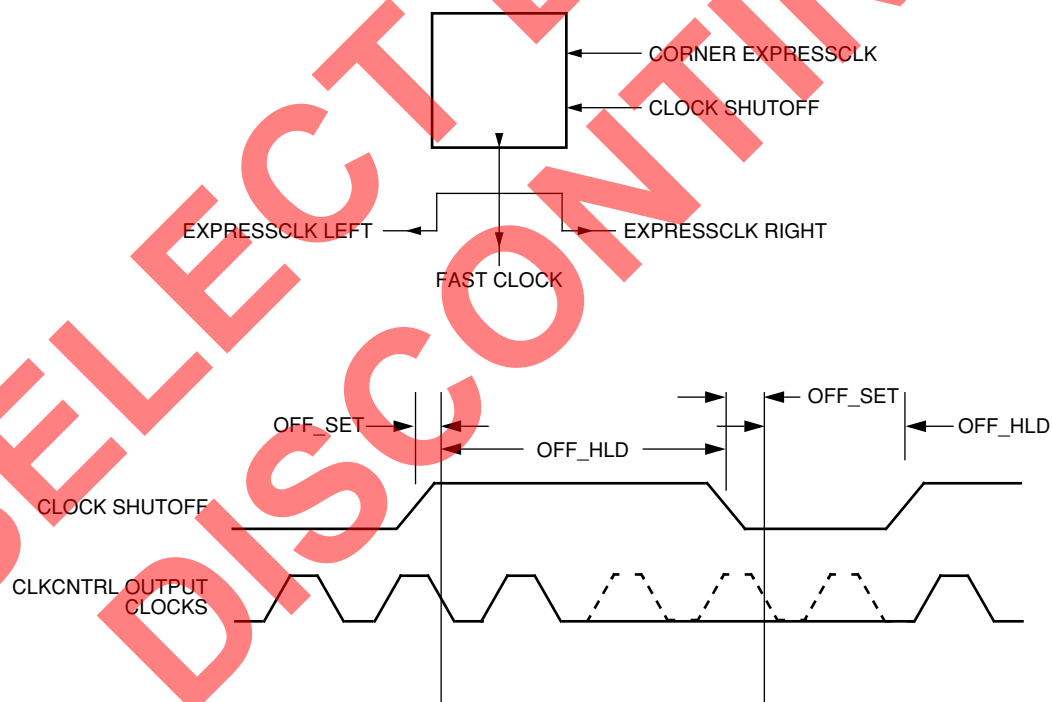
The start-up logic block is located in the lower right corner of the FPGA. This block can be configured to coordinate the relative timing of the release of GSRN, the activation of all user I/Os, and the assertion of the DONE signal at the end of configuration. If a start-up clock is used to time these events, the start-up clock can come from CCLK, or it can be routed into the start-up block using lower right corner routing resources. These signals are described in the Start-Up subsection of the FPGA States of Operation section.

Clock Control (CLKCNTRL) and StopCLK

There is one CLKCNTRL block in the MID section of the interquad routing on each side of the FPGA. This block is used to selectively distribute the fast clock to the PLC array and the left (top) and right (bottom) ExpressCLKs (ECKL and ECKR) to the side of the array on which the CLKCNTRL block resides.

The source clock for the CLKCNTRL block comes either from the ExpressCLK pad at the middle of the side of the FPGA or from the corner ExpressCLK route that comes from the corner ExpressCLK pad (at the lower left or upper right of the device, whichever is closer). The programmable clock manager ExpressCLK output can also be sourced to this corner routing for distribution at the two closest CLKCNTRL blocks.

Each CLKCNTRL block also features an invertible StopCLK shutoff input that is available from local routing. This feature may be used to glitchlessly stop and start the clock at the three outputs of each CLKCNTRL block and has the option of doing so on either the rising or falling edge of the clock. When the clock is halted based on its rising edge, it stops and stays at VDD. When it is stopped based on its falling edge, it stops and stays at GND. If the StopCLK shutoff signal meets the CLKCNTRL setup and hold times, the clock is stopped on the second clock cycle after the shutoff signal. A diagram of the bottom CLKCNTRL block and StopCLK timing is shown in Figure 35.



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Notes:

CLKCNTRL output clocks are ExpressCLK left and right and fast clock.

Clock shutoff shown active-high acting on clock falling edge.

Figure 35. Top CLKCNTRL Function Block

Special Function Blocks (continued)

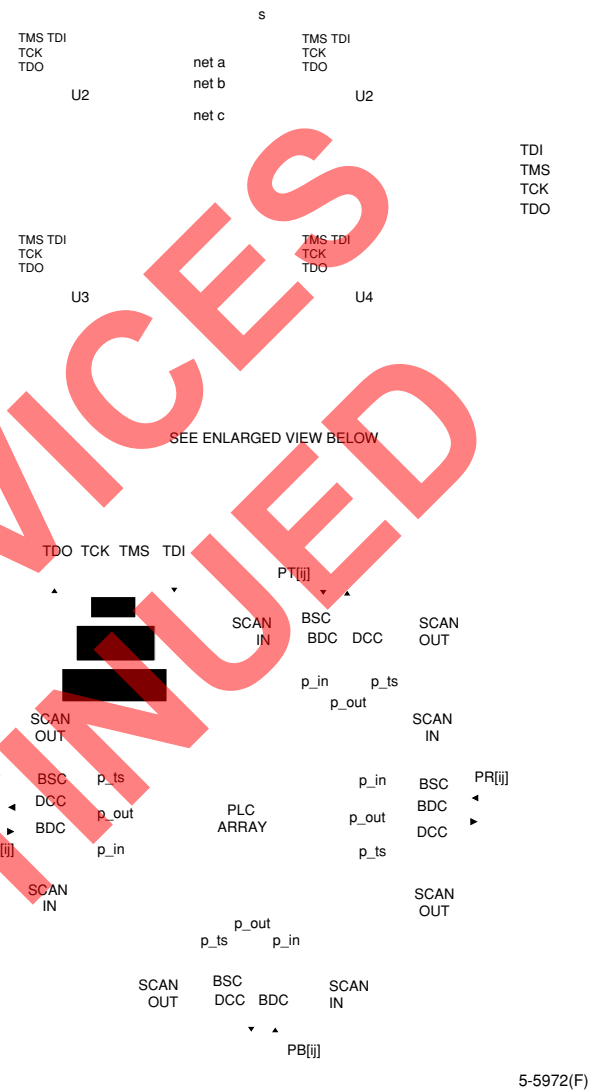
Boundary Scan

The increasing complexity of integrated circuits (ICs) and IC packages has increased the difficulty of testing printed-circuit boards (PCBs). To address this testing problem, the *IEEE* standard 1149.1/D1 (*IEEE* Standard Test Access Port and Boundary-Scan Architecture) is implemented in the *ORCA* series of FPGAs. It allows users to efficiently test the interconnection between integrated circuits on a PCB as well as test the integrated circuit itself. The *IEEE* 1149.1/D1 standard is a well-defined protocol that ensures interoperability among boundary-scan (BSCAN) equipped devices from different vendors.

The *IEEE* 1149.1/D1 standard defines a test access port (TAP) that consists of a four-pin interface with an optional reset pin for boundary-scan testing of integrated circuits in a system. The *ORCA* Series FPGA provides four interface pins: test data in (TDI), test mode select (TMS), test clock (TCK), and test data out (TDO). The $\overline{\text{PRGM}}$ pin used to reconfigure the device also resets the boundary-scan logic.

The user test host serially loads test commands and test data into the FPGA through these pins to drive outputs and examine inputs. In the configuration shown in Figure 36, where boundary scan is used to test ICs, test data is transmitted serially into TDI of the first BSCAN device (U1), through TDO/TDI connections between BSCAN devices (U2 and U3), and out TDO of the last BSCAN device (U4). In this configuration, the TMS and TCK signals are routed to all boundary-scan ICs in parallel so that all boundary-scan components operate in the same state. In other configurations, multiple scan paths are used instead of a single ring. When multiple scan paths are used, each ring is independently controlled by its own TMS and TCK signals.

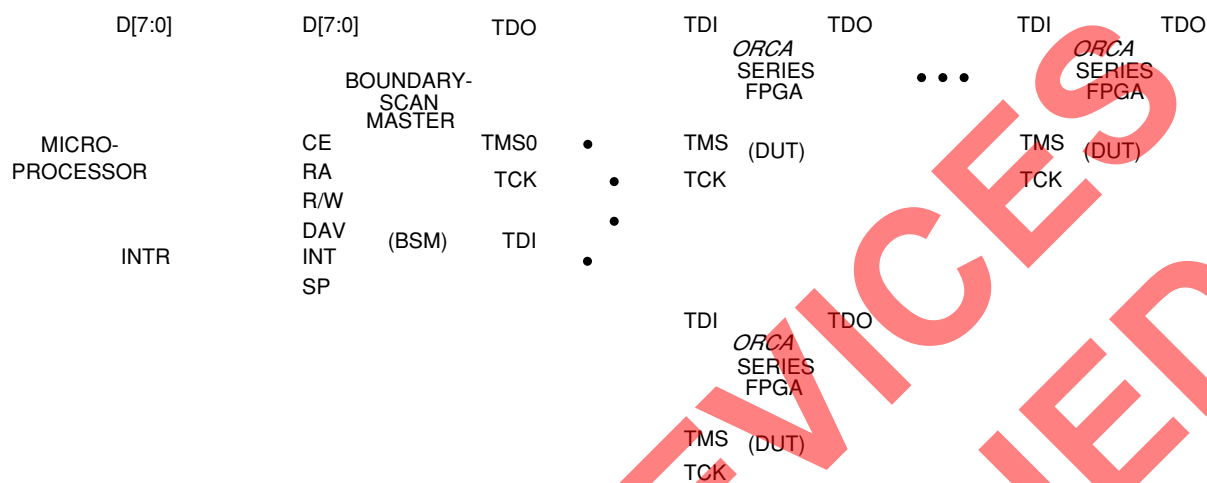
Figure 37 provides a system interface for components used in the boundary-scan testing of PCBs. The three major components shown are the test host, boundary-scan support circuit, and the devices under test (DUTs). The DUTs shown here are *ORCA* Series FPGAs with dedicated boundary-scan circuitry. The test host is normally one of the following: automatic test equipment (ATE), a workstation, a PC, or a microprocessor.



Key: BSC = boundary-scan cell, BDC = bidirectional data cell, and DCC = data control cell.

Figure 36. Printed-Circuit Board with Boundary-Scan Circuitry

Special Function Blocks (continued)



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Figure 37. Boundary-Scan Interface

The boundary-scan support circuit shown in Figure 37 is the 497AA Boundary-Scan Master (BSM). The BSM off-loads tasks from the test host to increase test throughput. To interface between the test host and the DUTs, the BSM has a general microprocessor interface and provides parallel-to-serial/serial-to-parallel conversion, as well as three 8K data buffers. The BSM also increases test throughput with a dedicated automatic test-pattern generator and with compression of the test response with a signature analysis register. The PC-based boundary-scan test card/software allows a user to quickly prototype a boundary-scan test setup.

Table 13. Boundary-Scan Instructions

| Code | Instruction |
|------|---------------------------------|
| 000 | EXTEST |
| 001 | PLC Scan Ring 1 (PSR1)/USERCODE |
| 010 | RAM Write (RAM_W) |
| 011 | IDCODE |
| 100 | SAMPLE/PRELOAD |
| 101 | PLC Scan Ring 2 (PSR2) |
| 110 | RAM Read (RAM_R) |
| 111 | BYPASS |

Boundary-Scan Instructions

The ORCA Series boundary-scan circuitry is used for three mandatory IEEE 1149.1/D1 tests (EXTEST, SAMPLE/PRELOAD, BYPASS), the optional IEEE 1149.1/D1 IDCODE instruction, and five ORCA-defined instructions. The 3-bit wide instruction register supports the nine instructions listed in Table 13, where the use of PSR1 or USERCODE is selectable by a bit stream option.

Microprocessor Interface (MPI) (continued)**MPI Setup and Control**

The MPI has a series of addressable registers that provide MPI control and status, configuration and readback data transfer, FPGA device identification, and a dedicated user scratchpad register. All registers are 8 bits wide. The address map for these registers and the user-logic address space are shown in Table 19, followed by descriptions of the register and bit functions. Note that for all registers, the most significant bit is bit 7, and the least significant bit is bit 0.

Table 19. MPI Setup and Control Registers

| Address (Hex) | Register |
|---------------|--|
| 00 | Control Register 1. |
| 01 | Control Register 2. |
| 02 | Scratchpad Register. |
| 03 | Status Register. |
| 04 | Configuration/Readback Data Register. |
| 05 | Readback Address Register 1 (bits [7:0]). |
| 06 | Readback Address Register 2 (bits [15:8]). |
| 07 | Device ID Register 1 (bits [7:0]). |
| 08 | Device ID Register 2 (bits [15:8]). |
| 09 | Device ID Register 3 (bits [23:16]). |
| 0A | Device ID Register 4 (bits [31:24]). |
| 0B—0F | Reserved. |
| 10—1F | User-definable Address Space. |

Control Register 1

The MPI control register 1 is a read/write register. The host processor writes a control byte to configure the MPI. It is readable by the host processor to verify the status of control bits previously written.

Table 20. MPI Setup and Control Registers Descriptions

| Bit # | Description |
|-------|--|
| Bit 0 | GSR Input. Setting this bit to a 1 invokes a global set/reset on the FPGA. The host processor must return this bit to a 0 to remove the GSR signal. GSR does not affect the registers at MPI addresses 0 through F hexadecimal or any configuration registers. Default state = 0. |
| Bit 1 | Reserved. |
| Bit 2 | Reserved. |
| Bit 3 | Reserved. |
| Bit 4 | Reserved. |
| Bit 5 | RD_CFG Input. Changing this bit to a 0 after configuration will initiate readback. The host processor must return this bit to a 1 to remove the RD_CFG signal. Since this bit works exactly like the RD_CFG input pin, please see the FPGA pin descriptions for more information on this signal. Default state = 1. |
| Bit 6 | Reserved. |
| Bit 7 | PRGM Input. Setting this bit to a 0 causes the FPGA to begin configuration and resets the boundary-scan circuitry. The host processor must return this bit to a 1 to remove the PRGM signal. Since this bit works exactly like the PRGM input pin (except that it does not reset the MPI), please see the FPGA pin descriptions for more information on this signal. Default state = 1. |

Microprocessor Interface (MPI) (continued)

Device ID Registers

The MPI device ID is broken into four registers holding 1 byte each. The device ID that is available through the MPI is the same as the boundary-scan ID code, except that the device ID in the MPI has a reverse bit order. There is no means to overwrite any of the device ID as can be done with the boundary-scan ID, but the MPI scratchpad register can be used as a personalization register. The format for the entire device ID is shown below followed by family and device values and the partitioning of the device ID into the four device ID registers.

Table 23. Device ID Code

| Version | Part* | Family | Manufacturer | MSB |
|---|---------|--------|--------------|-------|
| 4 bits | 10 bits | 6 bits | 11 bits | 1 bit |
| Example: (First version of OR3C80) 0000 0110100000 110000 00000011101 1 | | | | |

* PLC array size of FPGA.

Table 24 shows the family and device values for all parts covered by this data sheet.

Table 24. Series 3 Family and Device ID Values

| Part Name | Family ID (Hex) | Device ID (Hex) |
|-----------|-----------------|-----------------|
| OR3T20 | 03 | 0C |
| OR3T30 | 03 | 0E |
| OR3T55 | 03 | 12 |
| OR3C/T80 | 03 | 16 |
| OR3T125 | 03 | 1C |

Table 25 describes the device IDs for all parts covered by this data sheet as they are partitioned into the four registers found in the MPI.

Table 25. ORCA Series 3 Device ID Descriptions

| | |
|-----------------------------|---|
| Device ID Register 1 | |
| Bit 0 | Logic 1. This bit is always a one. |
| Bits [7:1] | 0011101, the 7 least significant bits of the manufacturer ID. |
| Device ID Register 2 | |
| Bits [3:0] | 0000, the 4 most significant bits of the manufacturer ID. |
| Bits [7:4] | The 4 least significant bits of the 10-bit part number. |
| Device ID Register 3 | |
| Bits [5:0] | The 6 most significant bits of the 10-bit part number. |
| Bits [7:6] | The 2 least significant bits of the device family code. |
| Device ID Register 4 | |
| Bits [3:0] | The 4 most significant bits of the device family code. |
| Bits [7:4] | The 4-bit device version code. |

Programmable Clock Manager (PCM) (continued)**PCM Detailed Programming**

Descriptions of bit fields and individual control bits in the PCM control registers are provided in Table 31. Refer to Figure 46 for more information on the location of the PCM elements that are discussed. In the following discussion, the duty cycle is in the percentage of the clock period where the clock is high.

Table 31. PCM Control Registers

| Bit # | Function |
|---|---|
| Register 0 Divider 0 Programming | |
| Bits [3:0] | 4-Bit Divider, DIV0, Value. This value enables the input clock to immediately be divided by a value from 1 to 8. A 0 value (the default) indicates that DIV0 is bypassed (no division). Bypass incurs less delay than dividing by 1. Hexadecimal values greater than 8 for bits [3:0] yield their modulo 8 value. For example, if bits [3:0] are 1001 (9 hex), the result is divide by 1 (remainder $9/8 = 1$). |
| Bits [6:4] | Reserved. |
| Bit 7 | DIV 0 Reset Bit. DIV0 may not be reset by GSRN depending on the value of register 7, bit 7. This bit may be set to 1 to reset DIV0 to its default value. Bit 0 must be set to 0 (the default) to remove the reset. |
| Register 1 Divider 1 Programming | |
| Bits [3:0] | 4-Bit Divider, DIV1, Value. This value enables the feedback clock to be divided by a value from 1 to 8. A 0 value (the default) indicates that DIV1 is bypassed (no division). Bypass incurs less delay than dividing by 1. Hexadecimal values greater than 8 for bits [3:0] yield their modulo 8 value. For example, if bits [3:0] are 1001 (9 hex), the result is divide by 1 (remainder $9/8 = 1$). |
| Bits [6:4] | Reserved. |
| Bit 7 | DIV1 Reset Bit. DIV1 may not be reset by GSRN, depending on the value of register 7, bit 7. This bit may be set to 1 to reset DIV1 to its default value. Bit 0 must be set to 0 (the default) to remove the reset. |
| Register 2 Divider 2 Programming | |
| Bits [3:0] | 4-Bit Divider, DIV2, Value. This value enables the tapped delay line output clock driven onto ExpressCLK to be divided by a value from 1 to 8. A 0 value (the default) indicates that DIV2 is bypassed (no division). Bypass incurs less delay than dividing by 1. Hexadecimal values greater than 8 for bits [3:0] yield their modulo 8 value. For example, if bits [3:0] are 1001 (9 hex), the result is divide by 1 (remainder $9/8 = 1$). |
| Bits [6:4] | Reserved. |
| Bit 7 | DIV2 Reset Bit. DIV2 may not be reset by GSRN, depending on the value of register 7, bit 7. This bit may be set to 1 to reset DIV2 to its default value. Bit 7 must be set to 0 (the default) to remove the reset. |
| Register 3 DLL 2x Duty-Cycle Programming | |
| Bits [2:0] | Duty-cycle selection for the doubled clock period associated with the input clock high. The duty cycle is (value of bit 6) * 50% + ((value of bits [2:0]) + 1) * 6.25%. See the description for bit 6. |
| Bits [5:3] | Duty-cycle selection for the doubled clock period associated with the input clock low. The duty cycle is (value of bit 7) * 50% + ((value of bits [2:0]) + 1) * 6.25%. See the description for bit 7. |
| Bit 6 | Master duty-cycle control for the first clock period of the doubled clock: 0 = less than or equal to 50%, 1 = greater than 50%. |
| Bit 7 | Master duty-cycle control for the second clock period of the doubled clock: 0 = less than or equal to 50%, 1 = greater than 50%. Example: Both clock periods having a 62.5% duty cycle, bits [7:0] are 11 001 001. |

FPGA States of Operation (continued)

If configuration has begun, an assertion of $\overline{\text{RESET}}$ or PRGM initiates an abort, returning the FPGA to the initialization state. The PRGM and $\overline{\text{RESET}}$ pins must be pulled back high before the FPGA will enter the configuration state. During the start-up and operating states, only the assertion of PRGM causes a reconfiguration.

In the master configuration modes, the FPGA is the source of configuration clock (CCLK). In this mode, the initialization state is extended to ensure that, in daisy-chain operation, all daisy-chained slave devices are ready. Independent of differences in clock rates, master mode devices remain in the initialization state an additional six internal clock cycles after INIT goes high.

When configuration is initiated, a counter in the FPGA is set to 0 and begins to count configuration clock cycles applied to the FPGA. As each configuration data frame is supplied to the FPGA, it is internally assembled into data words. Each data word is loaded into the internal configuration memory. The configuration loading process is complete when the internal length count equals the loaded length count in the length count field, and the required end of configuration frame is written.

All OR3Cxx I/Os operate as TTL inputs during configuration (OR3Txxx I/Os are CMOS-only). All I/Os that are

not used during the configuration process are 3-stated with internal pull-ups.

Warning: During configuration, all OR3Txxx inputs have internal pull-ups enabled. If these inputs are driven to 5V, they will draw substantial current (≈ 5 ma). This is due to the fact that the inputs are pulled up to 3V.

During configuration, the PIC and PLC latches/FFs are held set/reset and the internal BDI buffers are 3-stated. The combinatorial logic begins to function as the FPGA is configured. Figure 50 shows the general waveform of the initialization, configuration, and start-up states.

Configuration

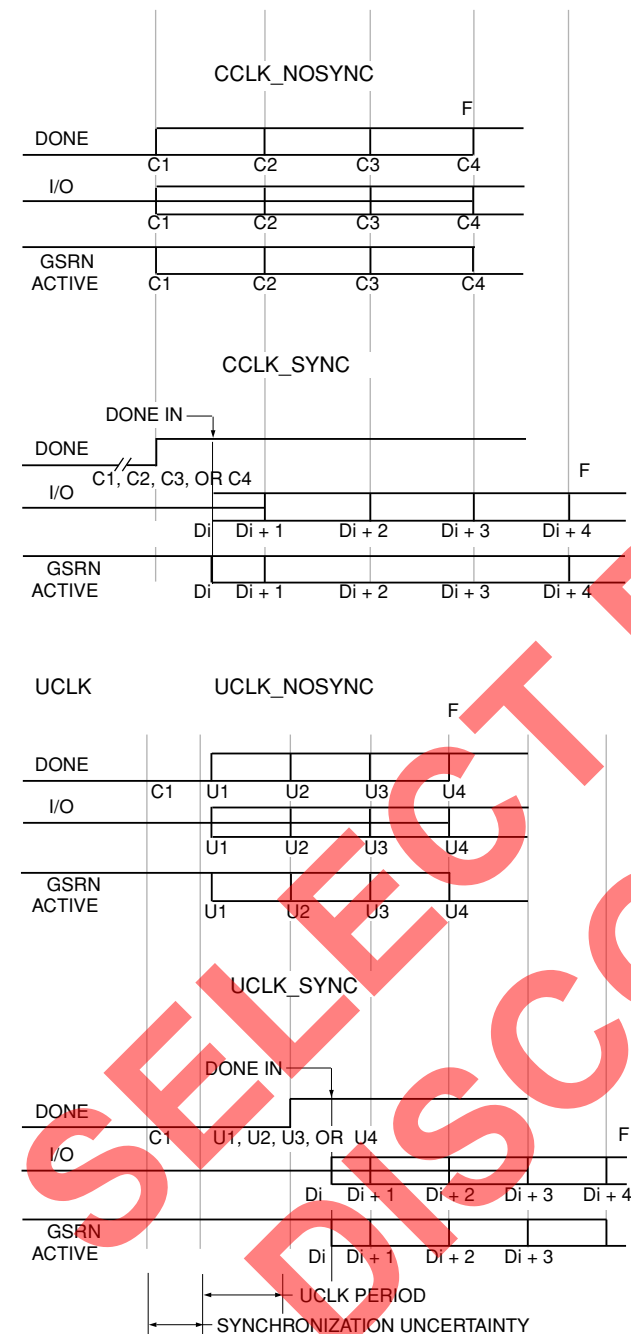
The ORCA Series FPGA functionality is determined by the state of internal configuration RAM. This configuration RAM can be loaded in a number of different modes. In these configuration modes, the FPGA can act as a master or a slave of other devices in the system. The decision as to which configuration mode to use is a system design issue. Configuration is discussed in detail, including the configuration data format and the configuration modes used to load the configuration data in the FPGA, following a description of the start-up state.



Figure 50. Initialization/Configuration/Start-Up Waveforms

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FPGA States of Operation (continued)



5-2761(F)

Figure 51. Start-Up Waveforms

Reconfiguration

To reconfigure the FPGA when the device is operating in the system, a low pulse is input into PRGM. The configuration data in the FPGA is cleared, and the I/Os not used for configuration are 3-stated. The FPGA then samples the mode select inputs and begins reconfiguration. When reconfiguration is complete, DONE is released, allowing it to be pulled high.

Partial Reconfiguration

All ORCA device families have been designed to allow a partial reconfiguration of the FPGA at any time. This is done by setting a bit stream option in the previous configuration sequence that tells the FPGA to not reset all of the configuration RAM during a reconfiguration. Then only the configuration frames that are to be modified need to be rewritten, thereby reducing the configuration time.

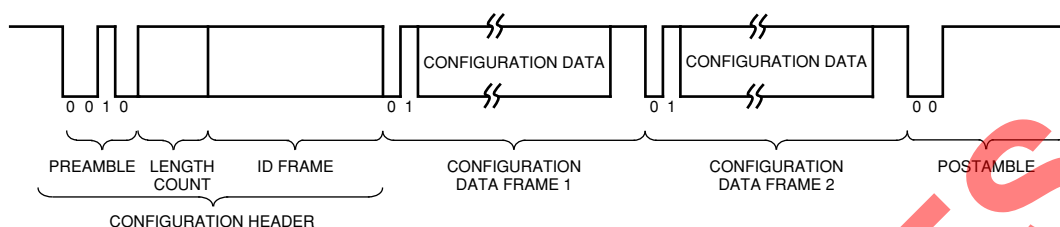
Other bit stream options are also available that allow one portion of the FPGA to remain in operation while a partial reconfiguration is being done. If this is done, the user must be careful to not cause contention between the two configurations (the bit stream resident in the FPGA and the partial reconfiguration bit stream) as the second reconfiguration bit stream is being loaded.

Other Configuration Options

There are many other configuration options available to the user that can be set during bit stream generation in ispLEVER. These include options to enable boundary scan and/or the microprocessor interface (MPI) and/or the programmable clock manager (PCM), readback options, and options to control and use the internal oscillator after configuration.

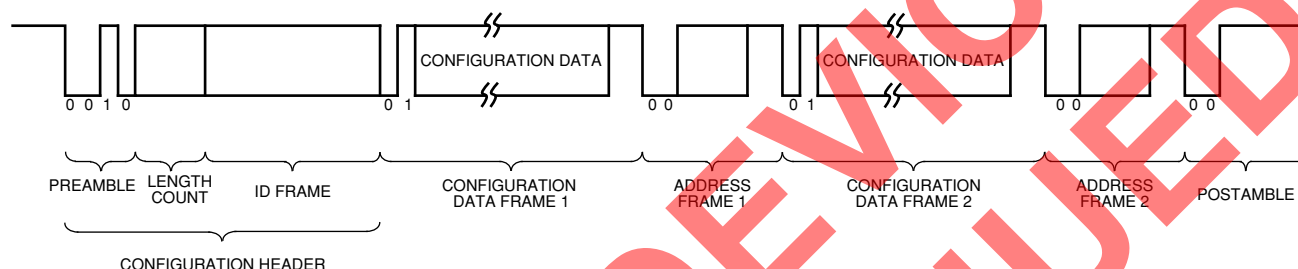
Other useful options that affect the next configuration (not the current configuration process) include options to disable the global set/reset during configuration, disable the 3-state of I/Os during configuration, and disable the reset of internal RAMs during configuration to allow for partial configurations (see above). For more information on how to set these and other configuration options, please see the ispLEVER documentation.

Configuration Data Format (continued)



5-5759(F)

Figure 52. Serial Configuration Data Format—Autoincrement Mode



5-5760(F)

Figure 53. Serial Configuration Data Format—Explicit Mode

Table 32. Configuration Frame Format and Contents

| | | |
|--|---------------------|--|
| Header | 11110010 | Preamble |
| | 24-bit Length Count | Configuration frame length. |
| | 11111111 | Trailing header—8 bits. |
| ID Frame | 0101 1111 1111 1111 | ID frame header. |
| | Configuration Mode | 00 = autoincrement, 01 = explicit. |
| | Reserved [41:0] | Reserved bits set to 0. |
| | ID | 20-bit part ID. |
| | Checksum | 8-bit checksum. |
| Configuration Data Frame (repeated for each data frame) | 11111111 | Eight stop bits (high) to separate frames. |
| | 01 | Data frame header. |
| | Data Bits | Number of data bits depends upon device. |
| | Alignment Bits = 0 | String of 0 bits added to bit stream to make frame header, plus data bits reach a byte boundary. |
| | Checksum | 8-bit checksum. |
| Configuration Address Frame | 11111111 | Eight stop bits (high) to separate frames. |
| | 00 | Address frame header. |
| | 14 Address Bits | 14-bit address of location to start data storage. |
| | Checksum | 8-bit checksum. |
| Postamble | 11111111 | Eight stop bits (high) to separate frames. |
| | 00 | Postamble header. |
| | 11111111 111111 | Dummy address. |
| | 1111111111111111 | 16 stop bits.* |

* In MPI configuration mode, the number of stop bits = 32.

Note: For slave parallel mode, the byte containing the preamble must be 11110010. The number of leading header dummy bits must be $(n * 8) + 4$, where n is any nonnegative integer and the number of trailing dummy bits must be $(n * 8)$, where n is any positive integer. The number of stop bits/frame for slave parallel mode must be $(x * 8)$, where x is a positive integer. Note also that the bit stream generator tool supplies a bit stream that is compatible with all configuration modes, including slave parallel mode.

Timing Characteristics (continued)

Table 43. Ripple Mode PFU Timing Characteristics (continued)

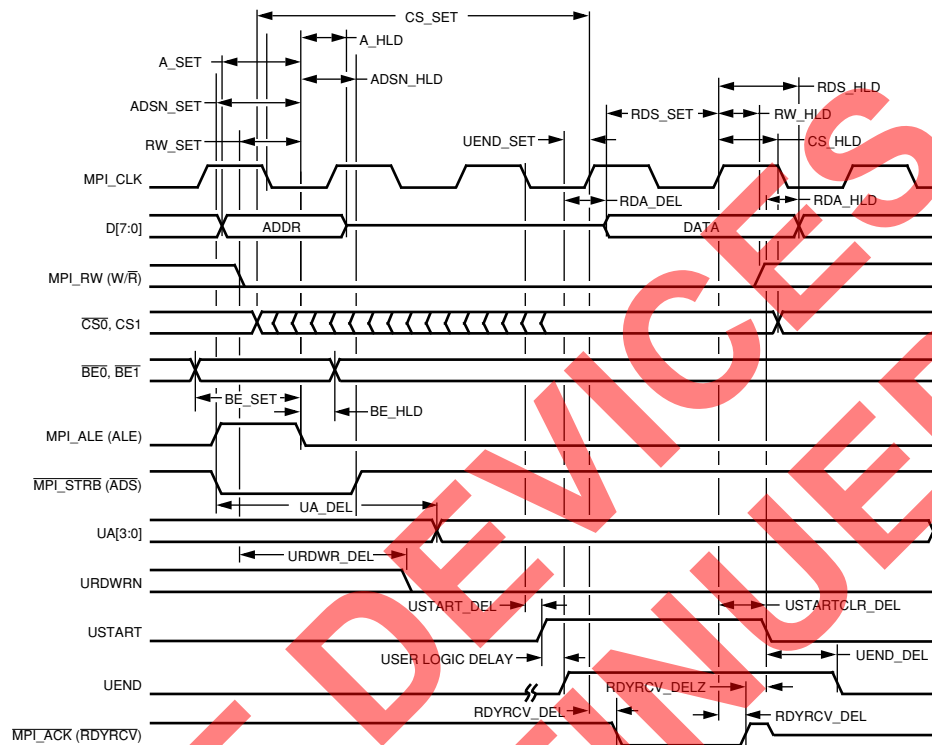
OR3Cxx Commercial: VDD = 5.0 V \pm 5%, 0 °C < TA < 70 °C; Industrial: VDD = 5.0 V \pm 10%, -40 °C < TA < +85 °C.

OR3Txx Commercial: VDD = 3.0 V to 3.6 V, 0 °C < TA < 70 °C; Industrial: VDD = 3.0 V to 3.6 V, -40 °C < TA < +85 °C.

| Parameter (TJ = +85 °C, VDD = min) | Symbol | Speed | | | | | | | | Unit |
|--|--------------|-------|-------|-----|------|-----|------|-----|------|------|
| | | -4 | | -5 | | -6 | | -7 | | |
| | | Min | Max | Min | Max | Min | Max | Min | Max | |
| Full Ripple Delays (byte wide): | | | | | | | | | | |
| Operands to Carry-out (Kz[1:0] to COUT) | RIPCO_DEL | — | 5.32 | — | 4.11 | — | 2.98 | — | 2.32 | ns |
| Operands to Carry-out (Kz[1:0] to FCOOUT) | RIPFCO_DEL | — | 5.30 | — | 4.10 | — | 2.98 | — | 2.32 | ns |
| Operands to PFU Out (Kz[1:0] to F[7:0]) | RIP_DEL | — | 7.37 | — | 5.60 | — | 4.18 | — | 3.10 | ns |
| Bitwise Operands to PFU Out (Kz[1:0] to F[z]) | FRIP_DEL | — | 2.34 | — | 1.80 | — | 1.32 | — | 1.05 | ns |
| Fast Carry-in to Carry-out (FCIN to COUT) | FCINCO_DEL | — | 2.59 | — | 1.99 | — | 1.43 | — | 1.14 | ns |
| Fast Carry-in to Fast Carry-out (FCIN to FCOOUT) | FCINFCO_DEL | — | 2.57 | — | 1.98 | — | 1.41 | — | 1.13 | ns |
| Carry-in to Carry-out (CIN to COUT) | CINCO_DEL | — | 3.47 | — | 2.65 | — | 1.79 | — | 1.43 | ns |
| Carry-in to Fast Carry-out (CIN to FCOOUT) | CINFCO_DEL | — | 3.46 | — | 2.64 | — | 1.78 | — | 1.43 | ns |
| Fast Carry-in PFU Out (FCIN to F[7:0]) | FCIN_DEL | — | 6.03 | — | 4.55 | — | 3.21 | — | 2.51 | ns |
| Carry-in PFU Out (CIN to F[7:0]) | CIN_DEL | — | 6.91 | — | 5.21 | — | 3.53 | — | 3.05 | ns |
| Add/Subtract to Carry-out (ASWE to COUT) | ASCO_DEL | — | 8.28 | — | 5.89 | — | 4.58 | — | 3.45 | ns |
| Add/Subtract to Carry-out (ASWE to FCOOUT) | ASFCO_DEL | — | 8.11 | — | 5.78 | — | 4.48 | — | 3.38 | ns |
| Add/Subtract to PFU Out (ASWE to F[7:0]) | AS_DEL | — | 10.66 | — | 7.55 | — | 5.85 | — | 4.38 | ns |
| Half Ripple Delays (nibble wide): | | | | | | | | | | |
| Operands to Carry-out (Kz[1:0] to COUT) | HRIPCO_DEL | — | 5.32 | — | 4.11 | — | 2.98 | — | 2.32 | ns |
| Operands to Fast Carry-out (Kz[1:0] to FCOOUT) | HRIPFCO_DEL | — | 5.30 | — | 4.10 | — | 2.98 | — | 2.32 | ns |
| Operands to PFU Out (Kz[1:0] to F[3:0]) | HRIP_DEL | — | 5.50 | — | 4.07 | — | 3.20 | — | 2.40 | ns |
| Bitwise Operands to PFU Out (Kz[1:0] to F[z]) | HFRIP_DEL | — | 2.34 | — | 1.80 | — | 1.32 | — | 1.05 | ns |
| Fast Carry-in to Carry-out (FCIN to COUT) | HFCINCO_DEL | — | 2.59 | — | 1.99 | — | 1.43 | — | 1.14 | ns |
| Fast Carry-in to Fast Carry-out (FCIN to FCOOUT) | HFCINFCO_DEL | — | 2.57 | — | 1.98 | — | 1.41 | — | 1.13 | ns |
| Carry-in to Carry-out (CIN to COUT) | HCINCO_DEL | — | 3.47 | — | 2.65 | — | 1.79 | — | 1.43 | ns |
| Carry-in to Carry-out (CIN to FCOOUT) | HCINFCO_DEL | — | 3.46 | — | 2.64 | — | 1.78 | — | 1.43 | ns |
| Fast Carry-in PFU Out (FCIN to F[3:0]) | HFCIN_DEL | — | 3.76 | — | 2.84 | — | 2.01 | — | 1.58 | ns |
| Carry-in PFU Out (CIN to F[3:0]) | HCIN_DEL | — | 4.65 | — | 3.50 | — | 2.33 | — | 2.12 | ns |
| Add/Subtract to Carry-out (ASWE to COUT) | HASCO_DEL | — | 8.28 | — | 5.89 | — | 4.58 | — | 3.45 | ns |
| Add/Subtract to Carry-out (ASWE to FCOOUT) | HASFCO_DEL | — | 8.11 | — | 5.78 | — | 4.48 | — | 3.38 | ns |
| Add/Subtract to PFU Out (ASWE to F[3:0]) | HAS_DEL | — | 9.12 | — | 6.49 | — | 4.86 | — | 3.69 | ns |

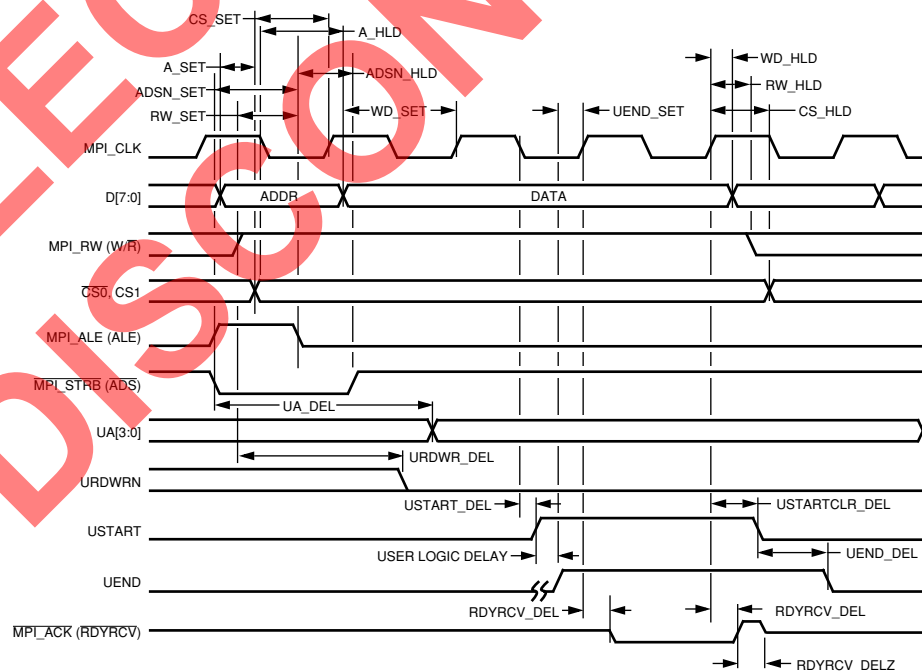
Note: The table shows worst-case delay for the ripple chain. ispLEVER reports the delay for individual paths within the ripple chain that will be less than or equal to those listed above.

Timing Characteristics (continued)



5-5831(F).b

Figure 71. MPI i960 User Space Read Timing



5-5830(F).b

Figure 72. MPI i960 User Space Write Timing

Timing Characteristics (continued)**Table 51. Boundary-Scan Timing Characteristics**OR3Cxx Commercial: VDD = 5.0 V \pm 5%, 0 °C < TA < 70 °C; Industrial: VDD = 5.0 V \pm 10%, -40 °C < TA < +85 °C.

OR3Txx Commercial: VDD = 3.0 V to 3.6 V, 0 °C < TA < 70 °C; Industrial: VDD = 3.0 V to 3.6 V, -40 °C < TA < +85 °C.

| Parameter | Symbol | Min | Max | Unit |
|----------------------------|------------------|------|------|------|
| TDI/TMS to TCK Setup Time | T _S | 25.0 | — | ns |
| TDI/TMS Hold Time from TCK | T _H | 0.0 | — | ns |
| TCK Low Time | T _{CL} | 50.0 | — | ns |
| TCK High Time | T _{CH} | 50.0 | — | ns |
| TCK to TDO Delay | T _D | — | 20.0 | ns |
| TCK Frequency | T _{TCK} | — | 10.0 | MHz |

TCK

T_S T_H

TMS

TDI

T_D

TDO

5-6764(F)

Figure 75. Boundary-Scan Timing Diagram

| Pin | OR3C/T80 Pad | OR3T125 Pad | Function | Pin | OR3C/T80 Pad | OR3T125 Pad | Function |
|------|--------------|-------------|-----------------|-----|--------------|-------------|----------------|
| AC30 | PL18D | PL22D | I/O | H29 | PL5D | PL6D | I/O |
| AC31 | PL17A | PL21A | I/O | J28 | PL4A | PL5D | I/O |
| AB29 | PL17B | PL21B | I/O-A13 | G31 | PL4B | PL4B | I/O |
| AB30 | PL17C | PL21C | I/O | G30 | PL4C | PL4C | I/O |
| AB31 | PL17D | PL21D | I/O | G29 | PL4D | PL4D | I/O |
| AA29 | PL16A | PL20A | I/O | H28 | PL3A | PL3A | I/O |
| Y28 | PL16B | PL20B | I/O | F31 | PL3B | PL3B | I/O |
| AA30 | PL16C | PL20C | I/O | F30 | PL3C | PL3C | I/O |
| AA31 | PL16D | PL20D | I/O-A12 | F29 | PL3D | PL3D | I/O |
| Y29 | PL15A | PL19A | I/O-A11/MPI_IRQ | E31 | PL2A | PL2A | I/O |
| W28 | PL15B | PL19D | I/O | E30 | PL2B | PL2B | I/O |
| Y30 | PL15C | PL18A | I/O | E29 | PL2C | PL2C | I/O |
| W29 | PL14A | PL18C | I/O | F28 | PL2D | PL2D | I/O-A0/MPI_BE0 |
| W30 | PL14B | PL18D | I/O | D31 | PL1A | PL1A | I/O |
| V28 | PL14C | PL17A | I/O-A10/MPI_BI | D30 | PL1B | PL1B | I/O |
| W31 | PL14D | PL17C | I/O | D29 | PL1C | PL1C | I/O |
| V29 | PL13A | PL17D | I/O | E28 | PL1D | PL1D | I/O |
| V30 | PL13B | PL16A | I/O | D27 | PRD_DATA | PRD_DATA | RD_DATA/TDO |
| V31 | PL13C | PL16C | I/O | C28 | PT1A | PT1A | I/O-TCK |
| U29 | PL13D | PL16D | I/O-A9/MPI_ACK | B28 | PT1B | PT1B | I/O |
| U30 | PL12A | PL15A | I/O-A8/MPI_RW | A28 | PT1C | PT1C | I/O |
| U31 | PL12B | PL15B | I/O | D26 | PT1D | PT1D | I/O |
| T30 | PL12C | PL15C | I/O | C27 | PT2A | PT2A | I/O |
| T28 | PL12D | PL15D | I/O | B27 | PT2B | PT2B | I/O |
| T29 | PL11A | PL14A | I/O-A7/MPI_CLK | A27 | PT2C | PT2C | I/O |
| R31 | PL11B | PL14B | I/O | C26 | PT2D | PT2D | I/O |
| R30 | PL11C | PL14C | I/O | B26 | PT3A | PT3A | I/O |
| R29 | PECKL | PECKL | I-ECKL | A26 | PT3B | PT3B | I/O |
| P31 | PL10A | PL13A | I/O-A6 | D24 | PT3C | PT3C | I/O |
| P30 | PL10B | PL13D | I/O | C25 | PT3D | PT3D | I/O |
| P29 | PL10C | PL12A | I/O | B25 | PT4A | PT4A | I/O-TMS |
| N31 | PL10D | PL12C | I/O | A25 | PT4B | PT4B | I/O |
| P28 | PL9A | PL12D | I/O-A5 | D23 | PT4C | PT4C | I/O |
| N30 | PL9B | PL11A | I/O-A4 | C24 | PT4D | PT4D | I/O |
| N29 | PL9C | PL11C | I/O | B24 | PT5A | PT5A | I/O |
| M30 | PL9D | PL11D | I/O | C23 | PT5B | PT5B | I/O |
| N28 | PL8A | PL10A | I/O | D22 | PT5C | PT5C | I/O |
| M29 | PL8C | PL10C | I/O | B23 | PT5D | PT5D | I/O |
| L31 | PL8D | PL10D | I/O | A23 | PT6A | PT6A | I/O-TDI |
| L30 | PL7A | PL9A | I/O-A3 | C22 | PT6B | PT6D | I/O |
| M28 | PL7B | PL9B | I/O | B22 | PT6C | PT7A | I/O |
| L29 | PL7C | PL9C | I/O | A22 | PT6D | PT7D | I/O |
| K31 | PL7D | PL9D | I/O | C21 | PT7A | PT8A | I/O |
| K30 | PL6A | PL8A | I/O-A2 | D20 | PT7B | PT8D | I/O |
| K29 | PL6B | PL8B | I/O | B21 | PT7C | PT9A | I/O |
| J31 | PL6C | PL8C | I/O | A21 | PT7D | PT9D | I/O |
| J30 | PL6D | PL8D | I/O | C20 | PT8A | PT10A | I/O-DOUT |
| K28 | PL5A | PL7D | I/O-A1/MPI_BE1 | D19 | PT8C | PT10D | I/O |
| J29 | PL5B | PL6B | I/O | B20 | PT8D | PT11A | I/O |
| H30 | PL5C | PL6C | I/O | C19 | PT9A | PT11C | I/O |

ψ_{JC}

This JEDEC designated parameter correlates the junction temperature to the case temperature. It is generally used to infer the junction temperature while the device is operating in the system. It is not considered a true thermal resistance, and it is defined by:

$$\psi_{JC} = \frac{T_J - T_C}{Q}$$

where T_C is the case temperature at top dead center, T_J is the junction temperature, and Q is the chip power. During the Θ_{JA} measurements described above, besides the other parameters measured, an additional temperature reading, T_C , is made with a thermocouple attached at top-dead-center of the case. ψ_{JC} is also expressed in units of °C/watt.

Θ_{JC}

This is the thermal resistance from junction to case. It is most often used when attaching a heat sink to the top of the package. It is defined by:

$$\Theta_{JC} = \frac{T_J - T_C}{Q}$$

The parameters in this equation have been defined above. However, the measurements are performed with the case of the part pressed against a water-cooled heat sink so as to draw most of the heat generated by the chip out the top of the package. It is this difference in the measurement process that differentiates Θ_{JC} from ψ_{JC} . Θ_{JC} is a true thermal resistance and is expressed in units of °C/watt.

Θ_{JB}

This is the thermal resistance from junction to board (a.k.a. Θ_{JL}). It is defined by:

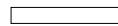
$$\Theta_{JB} = \frac{T_J - T_B}{Q}$$

where T_B is the temperature of the board adjacent to a lead measured with a thermocouple. The other parameters on the right-hand side have been defined above. This is considered a true thermal resistance, and the measurement is made with a water-cooled heat sink pressed against the board so as to draw most of the heat out of the leads. Note that Θ_{JB} is expressed in units of °C/watt, and that this parameter and the way it is measured is still in JEDEC committee.

Package Outline Diagrams (continued)

208-Pin SQFP2

Dimensions are in millimeters.



11



5-3828(F)



DETAIL C (SQFP2 CHIP-UP)

5-3828(F).a